

## CLAIMS

1. An epoxy resin composition for a printed wiring board, comprising an epoxy resin, a phenol novolac resin and a curing accelerator,  
characterized in that said epoxy resin comprises an epoxy (a) and an epoxy (b),  
wherein the epoxy (a) is a brominated epoxy resin, obtainable by reacting/mixing a bisphenol A epoxy resin with tetrabromobisphenol A, said brominated epoxy resin having an epoxy equivalent of 350 g/eq to 470 g/eq and containing an n=0 component in a ratio of 20% to 35% in terms of area percentage in a GPC chart; and  
the epoxy (b) is one or more of bifunctional epoxy resins, obtainable by reacting epichlorohydrin with any one selected from the group consisting of bisphenol A, bisphenol F and tetrabromobisphenol A, said bifunctional epoxy resins having an n=0 component in a content of 60% or higher in term of area percentage in a GPC chart;  
said epoxy (a) and epoxy (b) are contained in total in an amount of 80% to 100% by weight, preferably 93% to 100% by weight, based on the total weight of the epoxy resin;  
said epoxy (a) is contained in an amount of 75% to 97% by weight, based on the total weight of the epoxy resin; and  
said epoxy resin has a bromine content of 18% to 30% by weight, based on the total weight of the epoxy resin.
2. An epoxy resin composition for a printed wiring board according to claim 1, characterized in that the phenol novolac resin is a phenol novolac resin, obtainable by reacting formaldehyde with one selected from the group consisting of phenol, cresol and bisphenol A; said phenol novolac resin containing a bifunctional component in an amount of 15% to 30%.
3. An epoxy resin composition for a printed wiring board according to claim 1 or 2, characterized in that an inorganic filler is contained.
4. An epoxy resin composition for a printed wiring board described in claim 3, characterized in that a glass powder and/or silica filler is contained.
5. A prepreg for a printed wiring board, characterized in that the prepreg is obtainable by impregnating a glass cloth with a varnish comprising an organic solvent and an epoxy resin composition for a printed wiring board according to any one of claims 1 to 4 and drying the varnish to B-stage.

6. A laminated board for a printed wiring board, a printed wiring board or a laminated printed wiring board, characterized in that a prepreg for a printed wiring board according to claim 5 is used for the preparation thereof.